



## **Hemlock Semiconductor Group**

### ***Fact Sheet***

The Hemlock Semiconductor Group ([www.hscpoly.com](http://www.hscpoly.com)) is comprised of two joint ventures: Hemlock Semiconductor Corporation and Hemlock Semiconductor, L.L.C. The companies are joint ventures of Dow Corning Corporation, Shin-Etsu Handotai and Mitsubishi Materials Corporation. Hemlock Semiconductor is a leading provider of polycrystalline silicon and other silicon-based products used in the manufacturing of semiconductor devices and solar cells and modules. Hemlock Semiconductor began its Michigan operations in 1961 and broke ground at its Tennessee location in 2009.

Polycrystalline silicon (polysilicon) is the cornerstone material used to produce solar cells that harvest energy from sunlight. An ultra-pure version of the material is also the base-material for silicon wafers used in electronic devices. About a third of all the silicon used in manufacturing solar panels and electronic devices worldwide is from polysilicon.

### **Fast facts about Hemlock Semiconductor Group:**

- The Michigan site began operation in 1961 and was the first fully integrated polycrystalline silicon plant in the nation.
- The Michigan site is headquartered in Hemlock, Michigan, in Saginaw County.
- The two joint ventures of Hemlock Semiconductor Group are each owned by Dow Corning Corporation (63.25%), Shin-Etsu Handotai Co., Ltd. (24.5%), and Mitsubishi Materials Corporation (12.25%)
- Is one of the world's leading suppliers of polycrystalline silicon products used in the manufacturing of energy producing solar cells and semiconductors used widely in the electronics industry
- Current Michigan site workforce: approximately 1800
- Current number of construction workers on-site in Michigan: 800 - 1200
- President and CEO of both companies: Richard S. Doornbos

### **History of Hemlock Semiconductor Group:**

#### ***Michigan Site***

- 1957: Dow Corning implements technology to manufacture polycrystalline silicon
- Year built: 1960, First year in production: 1961
- 1979: Hemlock Semiconductor Corporation formed as a wholly owned subsidiary of Dow Corning Corporation.
- 1984: Becomes a joint venture of Dow Corning and two of Japan's largest single-crystal wafer manufacturers, Shin-Etsu Handotai Co., Ltd. and Mitsubishi Materials Corporation.
- 1992: Receives ISO 9002 registration and expands production capacity by 20 percent.

- 1994 Becomes one of the world's largest producer/supplier of polycrystalline silicon.
- 1998: Completes expansion to produce 35 percent more polycrystalline silicon. Finishing expansion and technology enhancements provide an ultra-clean polycrystalline silicon product.
- 2005: Announces and begins construction on a \$500 million expansion that will increase capacity 100%.
- 2007: Announces and begins construction on a \$1 billion expansion at its Hemlock, Mich. facility. The expansion will increase the company's total annual output of polycrystalline silicon to 36,000 metric tons, an increase of 90 percent.
- 2008: Commences operation of \$500 million expansion announced in 2005 and increases its capacity to approximately 19,000 metric tons.
- 2008: Announces investment of up to \$1.0 billion to expand polysilicon manufacturing.
- 2009: Commences operation of phase 1 of the \$1 billion expansion announced in 2007 and increases its capacity to approximately 27,500 metric tons.

#### *Tennessee Site*

- 2008: The Shareholders of Hemlock Semiconductor Corporation form Hemlock Semiconductor L.L.C. to facilitate the development of a new site in Clarksville, Tennessee (U.S.A.).
- 2008: Announces investment up to \$1.2 billion to further meet growing solar demand.
  - Creating 500 initial jobs and up to 800 upon full completion of the site
  - Will require approximately 1,000 construction workers in the next 4-7 years.
- 2009: Site construction begins